

ABSTRACT OF THE DISCLOSURE

The present invention features an interposer that provides a high reliability interface between an LGA connector and a motherboard. The novel interposer overcomes the limitations of prior art interposers by including a stepped spacer for each solder interconnection which prevents the relaxation of mechanical contact force while ensuring the integrity of each solder interconnection. The interposer provides noble metal plated contact pads on a first surface to receive the contact members of an LGA connector, and contact pads for BGA solder connections for attachment to a motherboard. A description of the processes to manufacture the interposer is also disclosed.

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